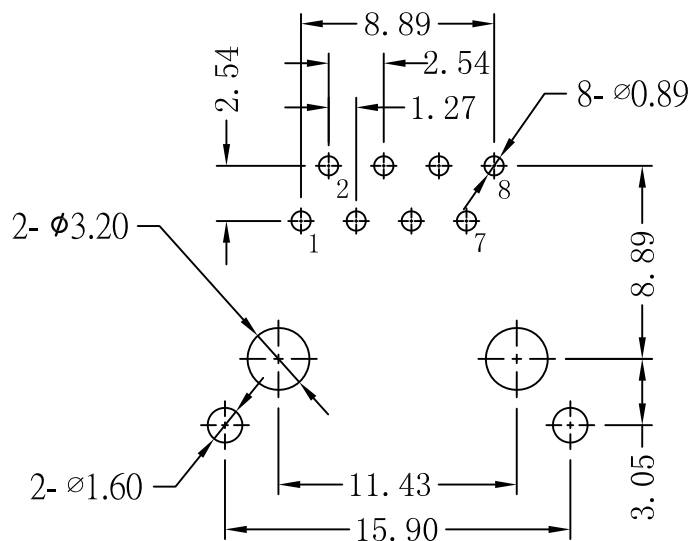
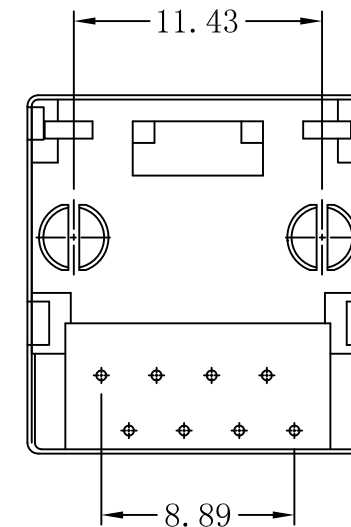
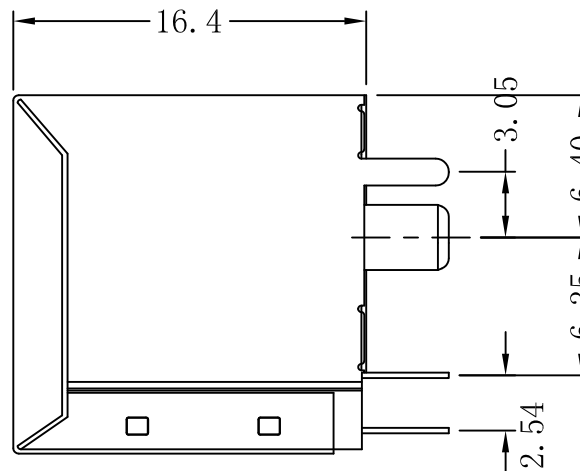
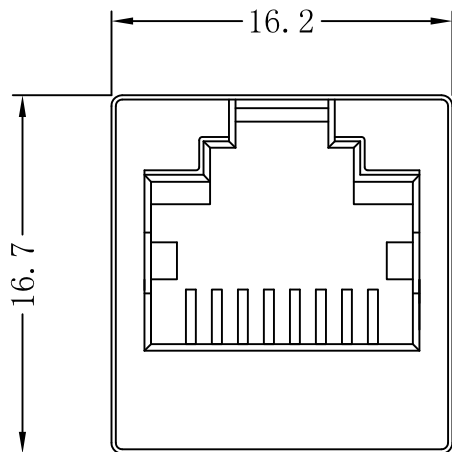


Mechanical:

REV.	ECN NO.	DESCRIPTION	DATE	APPD
A	REL		2010/05/24	



SUGGESTED PCB LAYOUT (TOP VIEW)

LPJE601XDNL

Gold Plating	"X"
Gold Flash	0
1.5u"	1
3u"	2
6u"	3
15u"	4
30u"	5
50u"	6

PCB JACK Specification

1. Insulation Resistance: 500MΩ MIN @ 500 VDC
2. Withstanding Voltage: AC1000V 50Hz or 60Hz 1min.
3. Durability: 600 Mating Circles MIN.
4. (1) Storage: -40°C to +85°C
(2) Operation: -40°C to +85°C
(3) Wave solder temperature: 230°C to 250°C, 5~10 Sec.



X:X	±0.30	APPD:	LINK-PP INT'L TECHNOLOGY CO., LIMITED
X:XX	±0.25	CHKD:	
X:XXX	±0.05	DR: TOM	TITLE: RJ45 1×1 CONNECTOR
ANGLES	±1°	UNIT: mm	PART NO.: LPJE6010DNL
	SCALE: 2/1	SHEET: 1/1	REV: A
			DWG NO: LP10052412